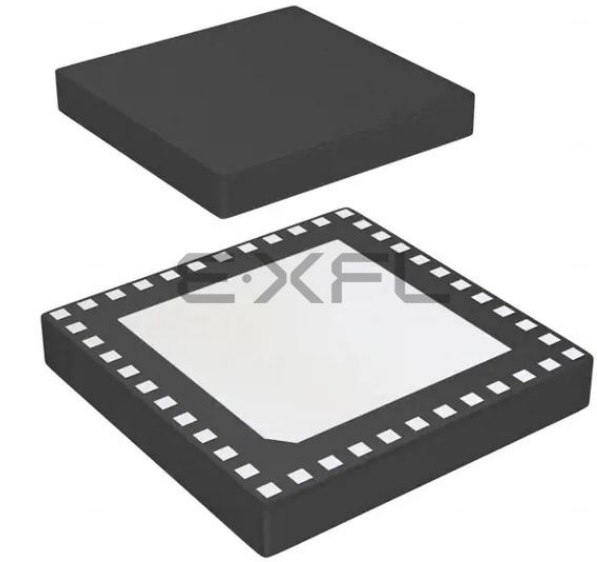

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

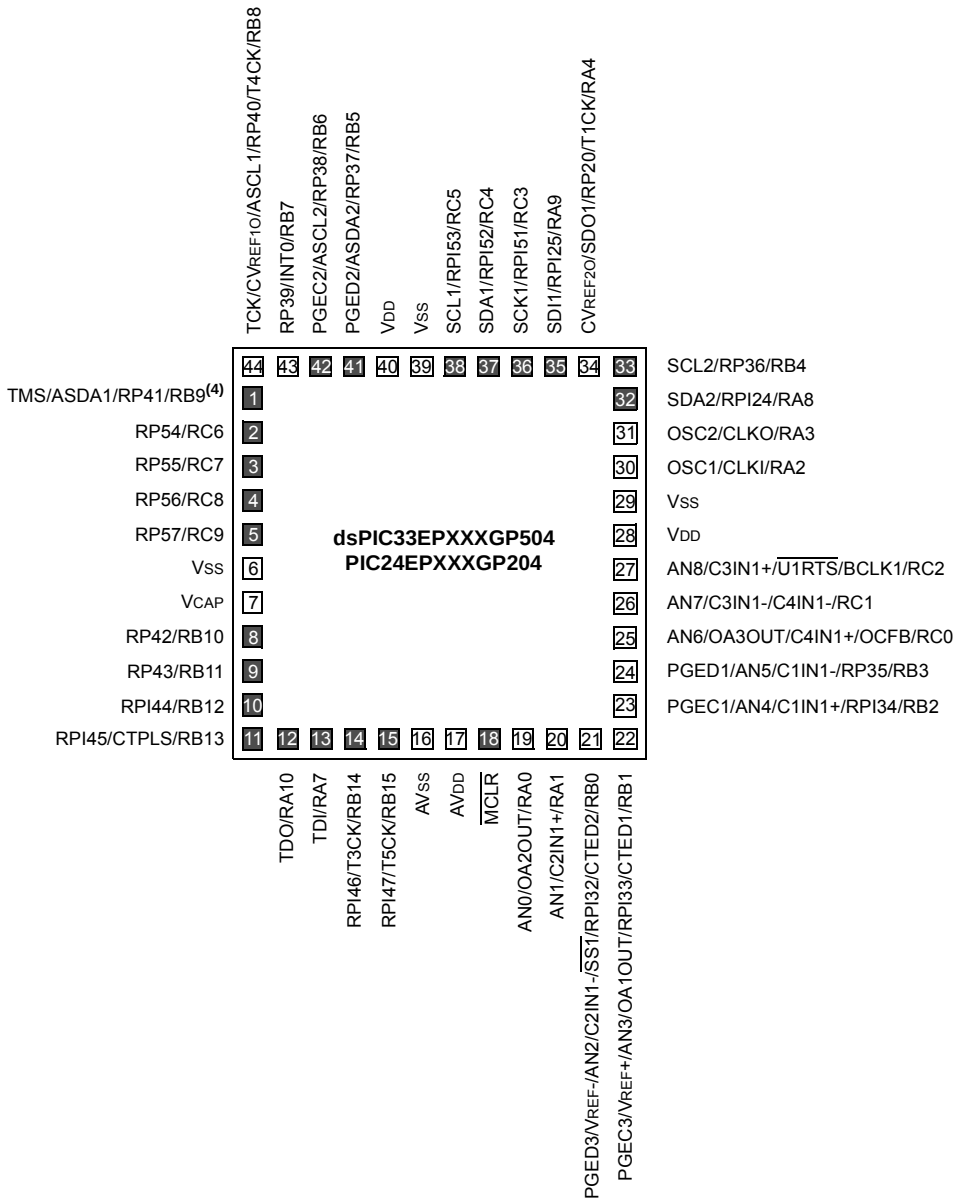
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep32mc204t-i-tl

Pin Diagrams (Continued)

44-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name(4)	Pin Type	Buffer Type	PPS	Description
AN0-AN15	I	Analog	No	Analog input channels.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/ CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
REFCLKO	O	—	Yes	Reference clock output.
IC1-IC4	I	ST	Yes	Capture Inputs 1 through 4.
OCFA	I	ST	Yes	Compare Fault A input (for Compare channels).
OCFB	I	ST	No	Compare Fault B input (for Compare channels).
OC1-OC4	O	—	Yes	Compare Outputs 1 through 4.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
RA0-RA4, RA7-RA12	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC13, RC15	I/O	ST	No	PORTC is a bidirectional I/O port.
RD5, RD6, RD8	I/O	ST	No	PORTD is a bidirectional I/O port.
RE12-RE15	I/O	ST	No	PORTE is a bidirectional I/O port.
RF0, RF1	I/O	ST	No	PORTF is a bidirectional I/O port.
RG6-RG9	I/O	ST	No	PORTG is a bidirectional I/O port.
T1CK	I	ST	No	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	No	Timer3 external clock input.
T4CK	I	ST	No	Timer4 external clock input.
T5CK	I	ST	No	Timer5 external clock input.
CTPLS	O	ST	No	CTMU pulse output.
CTED1	I	ST	No	CTMU External Edge Input 1.
CTED2	I	ST	No	CTMU External Edge Input 2.
$\overline{U1CTS}$	I	ST	No	UART1 Clear-To-Send.
$\overline{U1RTS}$	O	—	No	UART1 Ready-To-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
BCLK1	O	ST	No	UART1 IrDA® baud clock output.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name(4)	Pin Type	Buffer Type	PPS	Description
C1IN1- C1IN2- C1IN1+ OA1OUT C1OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 1 Negative Input 1. Comparator 1 Negative Input 2. Op Amp/Comparator 1 Positive Input 1. Op Amp 1 output. Comparator 1 output.
C2IN1- C2IN2- C2IN1+ OA2OUT C2OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 2 Negative Input 1. Comparator 2 Negative Input 2. Op Amp/Comparator 2 Positive Input 1. Op Amp 2 output. Comparator 2 output.
C3IN1- C3IN2- C3IN1+ OA3OUT C3OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 3 Negative Input 1. Comparator 3 Negative Input 2. Op Amp/Comparator 3 Positive Input 1. Op Amp 3 output. Comparator 3 output.
C4IN1- C4IN1+ C4OUT	I I O	Analog Analog —	No No Yes	Comparator 4 Negative Input 1. Comparator 4 Positive Input 1. Comparator 4 output.
CVREF1O CVREF2O	O O	Analog Analog	No No	Op amp/comparator voltage reference output. Op amp/comparator voltage reference divided by 2 output.
PGED1 PGEC1 PGED2 PGEC2 PGED3 PGEC3	I/O I I/O I I/O I	ST ST ST ST ST ST	No No No No No No	Data I/O pin for Programming/Debugging Communication Channel 1. Clock input pin for Programming/Debugging Communication Channel 1. Data I/O pin for Programming/Debugging Communication Channel 2. Clock input pin for Programming/Debugging Communication Channel 2. Data I/O pin for Programming/Debugging Communication Channel 3. Clock input pin for Programming/Debugging Communication Channel 3.
$\overline{\text{MCLR}}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	No	Ground reference for analog modules. This pin must be connected at all times.
VDD	P	—	No	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	No	CPU logic filter capacitor connection.
VSS	P	—	No	Ground reference for logic and I/O pins.
VREF+	I	Analog	No	Analog voltage reference (high) input.
VREF-	I	Analog	No	Analog voltage reference (low) input.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

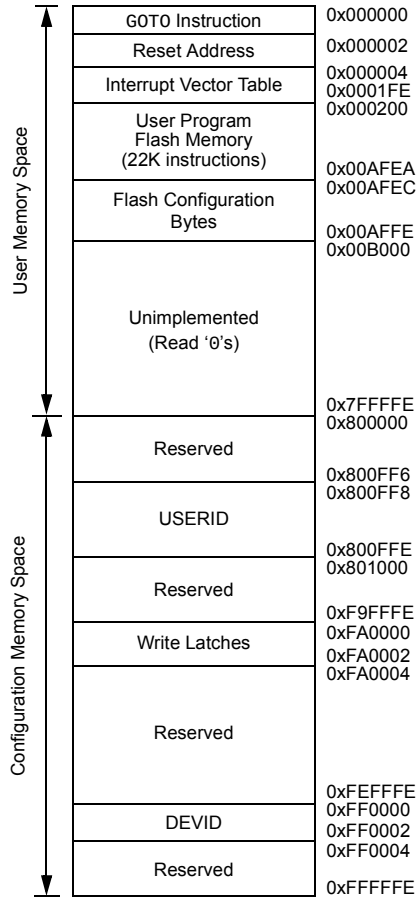
2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-2: PROGRAM MEMORY MAP FOR dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X AND PIC24EP64GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

7.0 INTERRUPT CONTROLLER

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Interrupts"** (DS70600) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X interrupt controller reduces the numerous peripheral interrupt request signals to a single interrupt request signal to the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU.

The interrupt controller has the following features:

- Up to eight processor exceptions and software traps
- Eight user-selectable priority levels
- Interrupt Vector Table (IVT) with a unique vector for each interrupt or exception source
- Fixed priority within a specified user priority level
- Fixed interrupt entry and return latencies

7.1 Interrupt Vector Table

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X Interrupt Vector Table (IVT), shown in Figure 7-1, resides in program memory starting at location, 000004h. The IVT contains seven non-maskable trap vectors and up to 246 sources of interrupt. In general, each interrupt source has its own vector. Each interrupt vector contains a 24-bit-wide address. The value programmed into each interrupt vector location is the starting address of the associated Interrupt Service Routine (ISR).

Interrupt vectors are prioritized in terms of their natural priority. This priority is linked to their position in the vector table. Lower addresses generally have a higher natural priority. For example, the interrupt associated with Vector 0 takes priority over interrupts at any other vector address.

7.2 Reset Sequence

A device Reset is not a true exception because the interrupt controller is not involved in the Reset process. The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices clear their registers in response to a Reset, which forces the PC to zero. The device then begins program execution at location, 0x000000. A GOTO instruction at the Reset address can redirect program execution to the appropriate start-up routine.

Note: Any unimplemented or unused vector locations in the IVT should be programmed with the address of a default interrupt handler routine that contains a RESET instruction.

REGISTER 9-5: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROON	—	ROSSLP	ROSEL	RODIV3(1)	RODIV2(1)	RODIV1(1)	RODIV0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROON:** Reference Oscillator Output Enable bit
1 = Reference oscillator output is enabled on the REFCLK pin(2)
0 = Reference oscillator output is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Run in Sleep bit
1 = Reference oscillator output continues to run in Sleep
0 = Reference oscillator output is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Oscillator crystal is used as the reference clock
0 = System clock is used as the reference clock

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divider bits(1)
1111 = Reference clock divided by 32,768
1110 = Reference clock divided by 16,384
1101 = Reference clock divided by 8,192
1100 = Reference clock divided by 4,096
1011 = Reference clock divided by 2,048
1010 = Reference clock divided by 1,024
1001 = Reference clock divided by 512
1000 = Reference clock divided by 256
0111 = Reference clock divided by 128
0110 = Reference clock divided by 64
0101 = Reference clock divided by 32
0100 = Reference clock divided by 16
0011 = Reference clock divided by 8
0010 = Reference clock divided by 4
0001 = Reference clock divided by 2
0000 = Reference clock

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The reference oscillator output must be disabled (ROON = 0) before writing to these bits.
2: This pin is remappable. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

15.1 Output Compare Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

15.1.1 KEY RESOURCES

- **"Output Compare"** (DS70358) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 17-1: QEI1CON: QEI1 CONTROL REGISTER (CONTINUED)

bit 6-4 **INTDIV<2:0>:** Timer Input Clock Prescale Select bits (interval timer, main timer (position counter), velocity counter and index counter internal clock divider select)(3)

111 = 1:128 prescale value
110 = 1:64 prescale value
101 = 1:32 prescale value
100 = 1:16 prescale value
011 = 1:8 prescale value
010 = 1:4 prescale value
001 = 1:2 prescale value
000 = 1:1 prescale value

bit 3 **CNTPOL:** Position and Index Counter/Timer Direction Select bit

1 = Counter direction is negative unless modified by external up/down signal
0 = Counter direction is positive unless modified by external up/down signal

bit 2 **GATEN:** External Count Gate Enable bit

1 = External gate signal controls position counter operation
0 = External gate signal does not affect position counter/timer operation

bit 1-0 **CCM<1:0>:** Counter Control Mode Selection bits

11 = Internal Timer mode with optional external count is selected
10 = External clock count with optional external count is selected
01 = External clock count with external up/down direction is selected
00 = Quadrature Encoder Interface (x4 mode) Count mode is selected

Note 1: When CCM<1:0> = 10 or 11, all of the QEI counters operate as timers and the PIMOD<2:0> bits are ignored.

2: When CCM<1:0> = 00, and QEA and QEB values match the Index Match Value (IMV), the POSCNTH and POSCNTL registers are reset. QEA/QEB signals used for the index match have swap and polarity values applied, as determined by the SWPAB and QEAPOL/QEBPOL bits.

3: The selected clock rate should be at least twice the expected maximum quadrature count rate.

21.0 ENHANCED CAN (ECAN™) MODULE (dsPIC33EPXXXGP/MC50X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Enhanced Controller Area Network (ECAN™)"** (DS70353) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

21.1 Overview

The Enhanced Controller Area Network (ECAN) module is a serial interface, useful for communicating with other CAN modules or microcontroller devices. This interface/protocol was designed to allow communications within noisy environments. The dsPIC33EPXXXGP/MC50X devices contain one ECAN module.

The ECAN module is a communication controller implementing the CAN 2.0 A/B protocol, as defined in the BOSCH CAN specification. The module supports CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system. The CAN specification is not covered within this data sheet. The reader can refer to the BOSCH CAN specification for further details.

The ECAN module features are as follows:

- Implementation of the CAN protocol, CAN 1.2, CAN 2.0A and CAN 2.0B
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbit/sec
- Automatic response to remote transmission requests
- Up to eight transmit buffers with application specified prioritization and abort capability (each buffer can contain up to 8 bytes of data)
- Up to 32 receive buffers (each buffer can contain up to 8 bytes of data)
- Up to 16 full (Standard/Extended Identifier) acceptance filters
- Three full acceptance filter masks
- DeviceNet™ addressing support
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- Programmable clock source
- Programmable link to Input Capture (IC2) module for time-stamping and network synchronization
- Low-power Sleep and Idle mode

The CAN bus module consists of a protocol engine and message buffering/control. The CAN protocol engine handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the receive registers.

22.2 CTMU Control Registers

REGISTER 22-1: CTMUCON1: CTMU CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN(1)	CTTRIG
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CTMUEN:** CTMU Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** CTMU Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Hardware modules are used to trigger edges (TMRx, CTEDx, etc.)
0 = Software is used to trigger edges (manual set of EDGxSTAT)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit(1)
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** ADC Trigger Control bit
1 = CTMU triggers ADC start of conversion
0 = CTMU does not trigger ADC start of conversion

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The ADC module Sample-and-Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitance measurement must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

23.4 ADC Control Registers

REGISTER 23-1: AD1CON1: ADC1 CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0, HC, HS	R/C-0, HC, HS
SSRC2	SSRC1	SSRC0	SSRCG	SIMSAM	ASAM	SAMP	DONE(3)
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	C = Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** ADC1 Operating Mode bit
1 = ADC module is operating
0 = ADC is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** ADC1 Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **ADDMABM:** DMA Buffer Build Mode bit
1 = DMA buffers are written in the order of conversion; the module provides an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer
0 = DMA buffers are written in Scatter/Gather mode; the module provides a Scatter/Gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer.

bit 11 **Unimplemented:** Read as '0'

bit 10 **AD12B:** ADC1 10-Bit or 12-Bit Operation Mode bit
1 = 12-bit, 1-channel ADC operation
0 = 10-bit, 4-channel ADC operation

bit 9-8 **FORM<1:0>:** Data Output Format bits
For 10-Bit Operation:
11 = Signed fractional (DOUT = sddd dddd dd00 0000, where s = .NOT.d<9>)
10 = Fractional (DOUT = dddd dddd dd00 0000)
01 = Signed integer (DOUT = ssss sssd dddd dddd, where s = .NOT.d<9>)
00 = Integer (DOUT = 0000 00dd dddd dddd)
For 12-Bit Operation:
11 = Signed fractional (DOUT = sddd dddd dddd 0000, where s = .NOT.d<11>)
10 = Fractional (DOUT = dddd dddd dddd 0000)
01 = Signed integer (DOUT = ssss sddd dddd dddd, where s = .NOT.d<11>)
00 = Integer (DOUT = 0000 dddd dddd dddd)

Note 1: See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for information on this selection.
2: This setting is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
3: Do not clear the DONE bit in software if Auto-Sample is enabled (ASAM = 1).

REGISTER 23-2: AD1CON2: ADC1 CONTROL REGISTER 2 (CONTINUED)

bit 1 **BUFM:** Buffer Fill Mode Select bit

1 = Starts the buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on next interrupt

0 = Always starts filling the buffer from the start address.

bit 0 **ALTS:** Alternate Input Sample Mode Select bit

1 = Uses channel input selects for Sample MUXA on first sample and Sample MUXB on next sample

0 = Always uses channel input selects for Sample MUXA

REGISTER 23-5: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NB1	CH123NB0	CH123SB
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NA1	CH123NA0	CH123SA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-9 **CH123NB<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample MUXB bits

In 12-bit mode (AD21B = 1), CH123NB is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
11	AN9	AN10	AN11
10(1,2)	OA3/AN6	AN7	AN8
0x	VREFL	VREFL	VREFL

bit 8 **CH123SB:** Channel 1, 2, 3 Positive Input Select for Sample MUXB bit

In 12-bit mode (AD21B = 1), CH123SB is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
1(2)	OA1/AN3	OA2/AN0	OA3/AN6
0(1,2)	OA2/AN0	AN1	AN2

bit 7-3 **Unimplemented:** Read as '0'

bit 2-1 **CH123NA<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample MUXA bits

In 12-bit mode (AD21B = 1), CH123NA is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
11	AN9	AN10	AN11
10(1,2)	OA3/AN6	AN7	AN8
0x	VREFL	VREFL	VREFL

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

REGISTER 25-5: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **HLMS:** High or Low-Level Masking Select bits
1 = The masking (blanking) function will prevent any asserted ('0') comparator signal from propagating
0 = The masking (blanking) function will prevent any asserted ('1') comparator signal from propagating

bit 14 **Unimplemented:** Read as '0'

bit 13 **OCEN:** OR Gate C Input Enable bit
1 = MCI is connected to OR gate
0 = MCI is not connected to OR gate

bit 12 **OCNEN:** OR Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to OR gate
0 = Inverted MCI is not connected to OR gate

bit 11 **OBEN:** OR Gate B Input Enable bit
1 = MBI is connected to OR gate
0 = MBI is not connected to OR gate

bit 10 **OBNEN:** OR Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to OR gate
0 = Inverted MBI is not connected to OR gate

bit 9 **OAEN:** OR Gate A Input Enable bit
1 = MAI is connected to OR gate
0 = MAI is not connected to OR gate

bit 8 **OANEN:** OR Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to OR gate
0 = Inverted MAI is not connected to OR gate

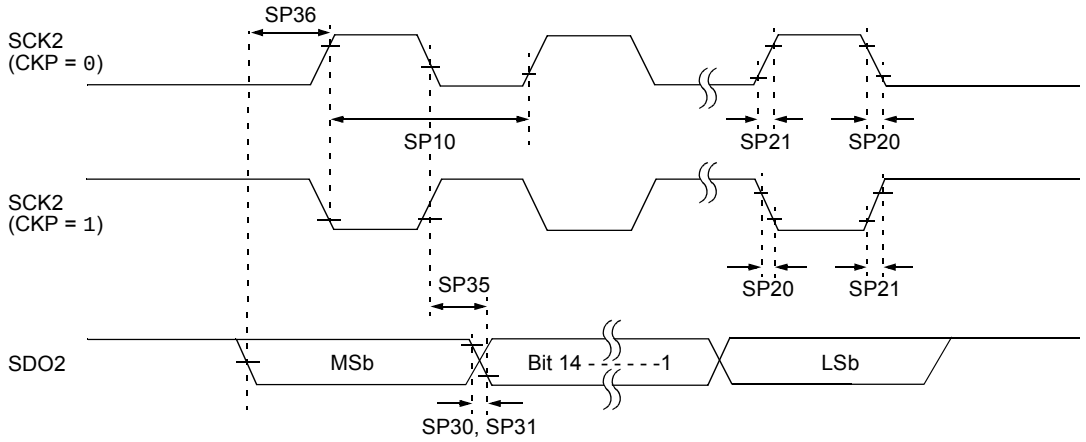
bit 7 **NAGS:** AND Gate Output Inverted Enable bit
1 = Inverted ANDI is connected to OR gate
0 = Inverted ANDI is not connected to OR gate

bit 6 **PAGS:** AND Gate Output Enable bit
1 = ANDI is connected to OR gate
0 = ANDI is not connected to OR gate

bit 5 **ACEN:** AND Gate C Input Enable bit
1 = MCI is connected to AND gate
0 = MCI is not connected to AND gate

bit 4 **ACNEN:** AND Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to AND gate
0 = Inverted MCI is not connected to AND gate

FIGURE 30-15: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-34: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK2 Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCK2 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK2 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

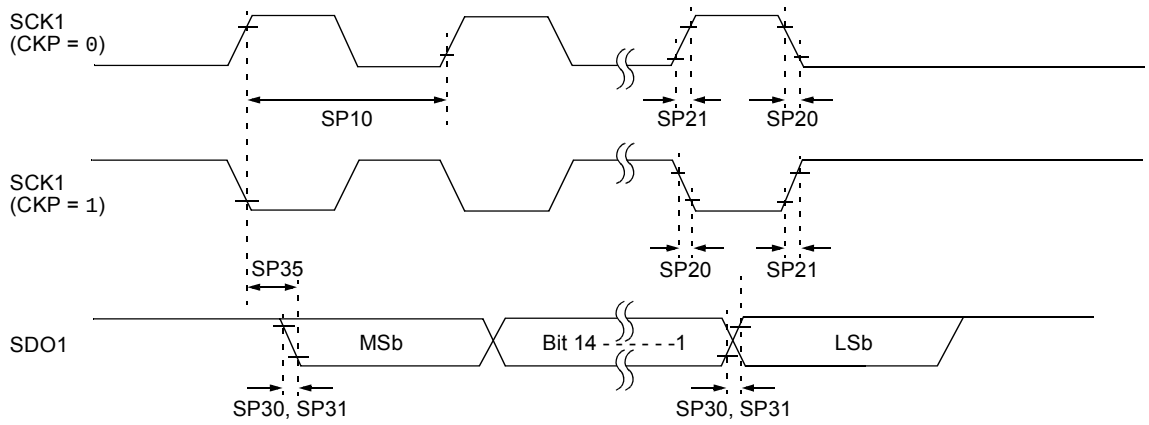
3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-41: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-42	—	—	0,1	0,1	0,1
10 MHz	—	Table 30-43	—	1	0,1	1
10 MHz	—	Table 30-44	—	0	0,1	1
15 MHz	—	—	Table 30-45	1	0	0
11 MHz	—	—	Table 30-46	1	1	0
15 MHz	—	—	Table 30-47	0	1	0
11 MHz	—	—	Table 30-48	0	0	0

FIGURE 30-22: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-45: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	$\overline{SDO1}$ Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

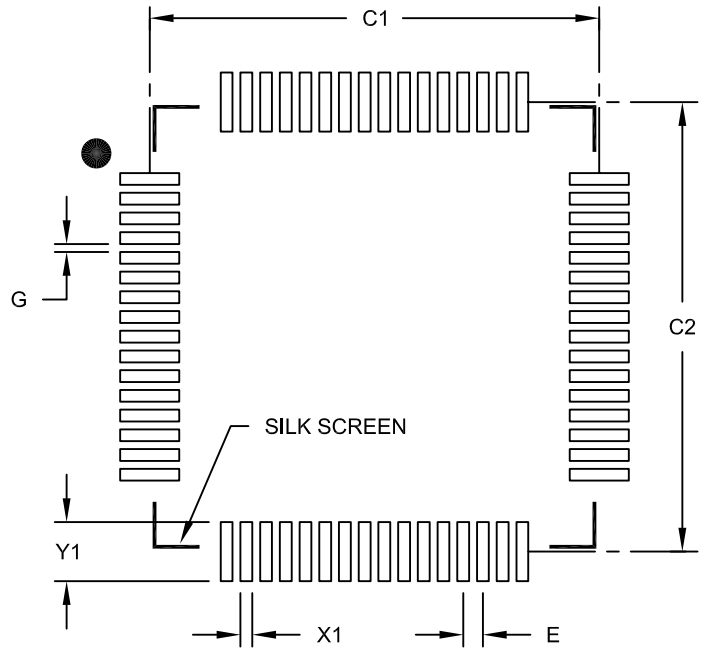
2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

Revision C (December 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

In addition, where applicable, new sections were added to each peripheral chapter that provide information and links to related resources, as well as helpful tips. For examples, see **Section 20.1 "UART Helpful Tips"** and **Section 3.6 "CPU Resources"**.

All occurrences of TLA were updated to VTLA throughout the document, with the exception of the pin diagrams (updated diagrams were not available at time of publication).

A new chapter, **Section 31.0 "DC and AC Device Characteristics Graphs"**, was added.

All other major changes are referenced by their respective section in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
"16-bit Microcontrollers and Digital Signal Controllers (up to 256-Kbyte Flash and 32-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog"	The content on the first page of this section was extensively reworked to provide the reader with the key features and functionality of this device family in an "at-a-glance" format.
Section 1.0 "Device Overview"	Updated the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X Block Diagram (see Figure 1-1), which now contains a CPU block and a reference to the CPU diagram. Updated the description and Note references in the Pinout I/O Descriptions for these pins: C1IN2-, C2IN2-, C3IN2-, OA1OUT, OA2OUT, and OA3OUT (see Table 1-1).
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers and Microcontrollers"	Updated the Recommended Minimum Connection diagram (see Figure 2-1).
Section 3.0 "CPU"	Updated the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X CPU Block Diagram (see Figure 3-1). Updated the Status register definition in the Programmer's Model (see Figure 3-2).
Section 4.0 "Memory Organization"	Updated the Data Memory Maps (see Figure 4-6 and Figure 4-11). Removed the DCB<1:0> bits from the OC1CON2, OC2CON2, OC3CON2, and OC4CON2 registers in the Output Compare 1 Through Output Compare 4 Register Map (see Table 4-10). Added the TRIG1 and TRGCON1 registers to the PWM Generator 1 Register Map (see Table 4-13). Added the TRIG2 and TRGCON2 registers to the PWM Generator 2 Register Map (see Table 4-14). Added the TRIG3 and TRGCON3 registers to the PWM Generator 3 Register Map (see Table 4-15). Updated the second note in **Section 4.7.1 "Bit-Reversed Addressing Implementation"**.
Section 8.0 "Direct Memory Access (DMA)"	Updated the DMA Controller diagram (see Figure 8-1).
Section 14.0 "Input Capture"	Updated the bit values for the ICx clock source of the ICTSEL<12:10> bits in the ICxCON1 register (see Register 14-1).
Section 15.0 "Output Compare"	Updated the bit values for the OCx clock source of the OCTSEL<2:0> bits in the OCxCON1 register (see Register 15-1). Removed the DCB<1:0> bits from the Output Compare x Control Register 2 (see Register 15-2).